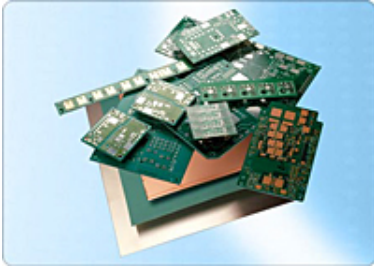

Item # Tlam /, Tlam™ System Circuit Boards Materials



Tlam™ System Circuit Boards Materials

Thermally Conductive Circuit Board Materials

Tlam™ thermally conductive printed circuit boards use Tpreg™ dielectric sheets in conjunction with copper foil and an integral metal base to provide circuit board laminate that has superior thermal management capabilities when compared to conventional FR4-based printed circuit boards (PCBs).

Tpreg™, a free standing thermally conductive dielectric sheet, Facilities single layer, multilayer and FR4-hybrid construction.

Tpreg™ is the only high thermal conductivity free-standing pre-preg available.

Our engineers routinely work with OEMs and fabricators to design circuit boards using the Tlam™ system.

Prototypes are available

Laird Technologies provide laminated IMPCB as a standard product. IMPCB incorporate a metal base plate (typically Aluminum or Copper), the dielectric (1KA or HTD) and the Copper circuit foil.

Tpreg 1KA is an extremely versatile conductive (3 W/mk) pre-preg. Tpreg 1KA can be used to make single layer (IMPCB) and multi-layer (DSL), bonding of FR-4 to aluminum, and thermally enhancing multi-layer FR-4 substrate constructions. The standard panel size offering is 18" x 24"

Base plate thickness range from 0.5 mm to 3 mm thick for both Aluminum and Copper.

Standard circuit copper weights are from 1/2 oz to 6 oz

Tpreg HTD is the only thermally conductive pre-preg material with 150 CUL RTI rating. Tpreg HTD is used to make single layer IMPCB substrates.

The standard panel size offering is 18" x 24"

FEATURES AND BENEFITS

- RoHS Complaint pre-Preg
- Standard FR-4 print and etch processing
- Low thermal resistance
- 3 w/mk thermal conductivity
- Available in multiple thicknesses
- UL recognized materials File No. E165095